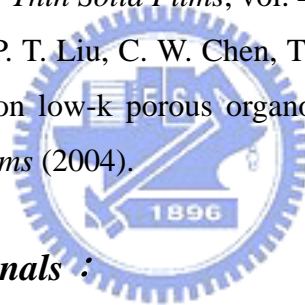


Publication List

International Regular Journals :

- [1] T. C. Chang, **T. M. Tsai**, P. T. Liu, Y. S. Mor, C. W. Chen, Y. J. Mei, J. T. Sheu, T. Y. Tseng, "The novel pattern method of low-k hybrid-organic-siloxane-polymer film using X-ray exposure," *Thin Solid Films*, Vol. 420-421, pp. 403-407, (2002).
- [2] T. C. Chang, **T. M. Tsai**, P. T. Liu, Y. C. Chang, H. Aoki, S. M. Sze, T. Y. Tseng, "Method to improve chemical-mechanical-planarization polishing rate of low-k methyl-silsesquiazane for ultralarge scale integrated interconnect application," *J. Vac. Sci. Technol. B*, vol. 22, no. 3, pp. 1196-1201, May/Jun (2004).
- [3] T. C. Chang, **T. M. Tsai**, P. T. Liu, C. W. Chen, S. T. Yan, H. Aoki, Y. C. Chang, T. Y. Tseng, "CMP of ultra low-k material porous-polysilazane (PPSZ) for interconnect applications," *Thin Solid Films*, vol. 447-448, pp. 524-530, (2004).
- [4] T. C. Chang, **T. M. Tsai**, P. T. Liu, C. W. Chen, T. Y. Tseng, "Study on the effect of electron beam curing on low-k porous organosilicate glass (OSG) material," accepted by *Thin Solid Films* (2004).



International Letter Journals :

- [1] T. C. Chang, **T. M. Tsai**, P. T. Liu, Y. S. Mor, C. W. Chen, J. T. Sheu, and T. Y. Tseng, "Direct patterning of low-k Hydrogen Silsesquioxane Using X-ray Exposure Technology," *Electrochem. and Solid-State Lett.*, **6**, G69, (2003).
- [2] T. C. Chang, **T. M. Tsai**, P. T. Liu, C. W. Chen, S. T. Yan, H. Aoki, Y. C. Chang, and T. Y. Tseng, "CMP of Low-k Methylsilsesquiazane with Oxygen Plasma Treatment for Multilevel Interconnect Applications" *Electrochem. and Solid-State Lett.*, **7 (6)**, G122-G124 (2004).

International Conferences :

- [1] **T. M. Tsai**, T. C. Chang, P. T. Liu, C. W. Chen, S. T. Yan, J. T. Peng, H. Aoki, T. Y. Tseng, "CMP of Low-k Material Methylsilsesquiazane (MSZ) for Interconnect Applications," *International Electron Devices and Materials Symposium*, Taipei, Taiwan, p. 360-363, 2002.
- [2] T. C. Chang, **T. M. Tsai**, P. T. Liu, C. W. Chen, S. T. Yan, Y. T. Chen, T. Y. Tseng,

“Study on the Effect of Electron Beam Curing on Low-k Organic Silica Glass (OSG) Material,” *International Conference on Metallurgical Coatings and Thin Films*, San Diego, CA, USA (2004).

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